









KPGF-1012GBRC-07

1 x 1 x 0.25 mm Full-Color Surface Mount LED

DESCRIPTIONS

- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- The Blue source color devices are made with InGaN Light Emitting Diode
- The Hyper-Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

FEATURES

- 1.0 mm x 1.0 mm SMD LED, 0.25 mm thickness
- · Low power consumption
- Package: 4000 pcs / reel
- Moisture sensitivity level: 3
- · Halogen-free
- · RoHS compliant

APPLICATIONS

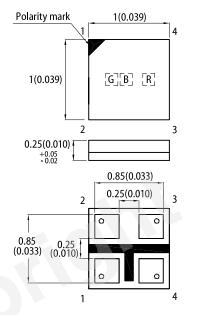
- Backlight
- · Status indicator
- Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

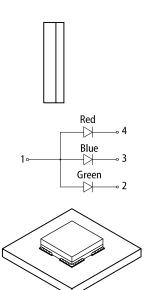
ATTENTION

Observe precautions for handling Electrostatic discharge sensitive devices



PACKAGE DIMENSIONS





RECOMMENDED SOLDERING PATTERN

(units: mm; tolerance: \pm 0.1) 0.25 0.4

> Mask open area ratio: 80% Mask thickness: 80~100um

- 1. All dimensions are in millimeters (inches).
- Tolerance is ±0.1(0.004") unless otherwise noted.
 The specifications, characteristics and technical data described in the datasheet are subject to
- change without prior notice.

 The device has a single mounting surface. The device must be mounted according to the specifications

SELECTION GUIDE

Part Number	Emitting Color	Lens Type		@ 5mA ^[2]	Viewing Angle [1]
Fait Number	(Material)	Lens Type	Min.	Тур.	201/2
KPGF-1012GBRC-07	☐ Green (InGaN)	Water Clear	80	220	
	■ Blue (InGaN)		10	23	150°
	■ Hyper Red (AlGaInP)		15	30	

- Notes.
 1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity / luminous flux: +/-15%.
- 3. Luminous intensity value is traceable to CIE127-2007 standards.





ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Counch of	Fueltting Colon	Value		Unit
Parameter	Symbol	Emitting Color	Тур.		
Wavelength at Peak Emission I _F = 5mA	λ_{peak}	Green Blue Hyper Red	515 460 632	-	nm
Dominant Wavelength I _F = 5mA	λ_{dom} [1]	Green Blue Hyper Red	525 465 624	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 5mA	Δλ	Green Blue Hyper Red	30 25 20	-	nm
Capacitance	С	Green Blue Hyper Red	45 100 25	-	pF
Forward Voltage I _F = 5mA	V _F ^[2]	Green Blue Hyper Red	2.85 2.8 1.95	3.3 3.3 2.3	V
Reverse Current (V _R = 5V)	I _R	Green Blue Hyper Red	-	50 50 10	μА
Temperature Coefficient of λ_{peak} I _F = 5mA, -10°C \leq T \leq 85°C	$TC_{\lambda peak}$	Green Blue Hyper Red	0.05 0.04 0.13	-	nm/°C
Temperature Coefficient of λ_{dom} I _F = 5mA, -10°C \leq T \leq 85°C	TC_{\lambdadom}	Green Blue Hyper Red	0.03 0.03 0.06	-	nm/°C
Temperature Coefficient of V_F I_F = 5mA, -10°C \leq T \leq 85°C	TC _v	Green Blue Hyper Red	-3 -3 -1.9	-	mV/°C

- 1. The dominant wavelength (λ d) above is the setup value of the sorting machine. (Tolerance λ d: ± 1 nm.) 2. Forward voltage: ± 0.1 V.
- Wavelength value is traceable to CIE127-2007 standards.
- 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter	Symbol	Value			1114
Parameter		Green	Blue	Hyper Red	Unit
Power Dissipation	P _D [1]	35			mW
Reverse Voltage	V _R	5	5	5	V
Junction Temperature	Tj	115	115	115	°C
Operating Temperature	T _{op}	-40 to +85			°C
Storage Temperature	T _{stg}	-40 to +100			°C
DC Forward Current	I _F ^[2]	10	10	10	mA
Peak Forward Current	I _{FM} ^[3]	50	50	50	mA
Electrostatic Discharge Threshold (HBM)	-	450	250	3000	V
Thermal Resistance (Junction / Ambient)	R _{th JA} [4]	740	690	770	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[4]	650	610	630	°C/W

Notes:

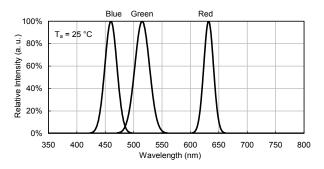
1. Within 35mW when multiple chips are lightened
2. The maximum ratings are valid for the case of lighting a single chip
When two chips are lift at the same time, each chip should be driven at a current lower than 50% of the absolute maximum ratings
When three chips are lift at the same time, each chip should be driven at a current lower than 30% of the absolute maximum ratings
When three chips are lift at the same time, each chip should be driven at a current lower than 30% of the absolute maximum ratings
3. Duty Cycle ≤ 1/20, Pulse Width = 1ms.
4. R_{th. 1.4}, R_{th. 2} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).
5. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



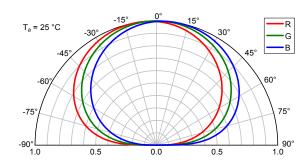


TECHNICAL DATA

RELATIVE INTENSITY vs. WAVELENGTH

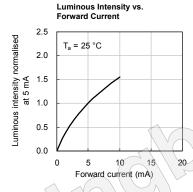


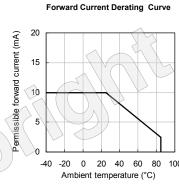
SPATIAL DISTRIBUTION

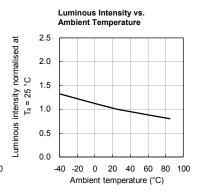


GREEN

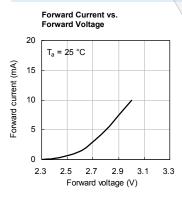
Forward Current vs. **Forward Voltage** T_a = 25 °C Forward current (mA) 15 10 5 0 2.7 2.3 2.5 2.9 3.1 Forward voltage (V)

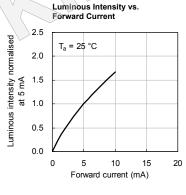


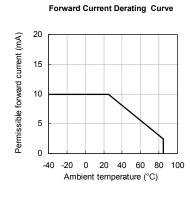


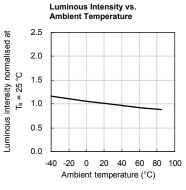


BLUE

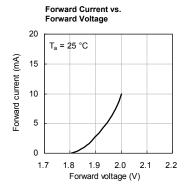


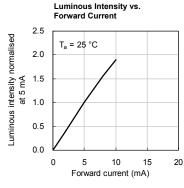


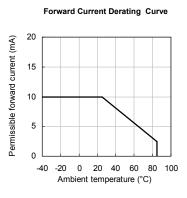


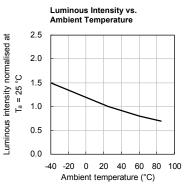


HYPER RED







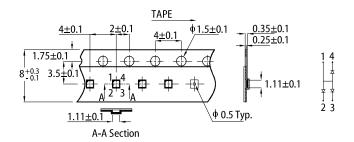




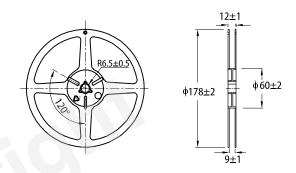
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

300 above 255°C (°C) 260°C max. 30s max. 10s max. 250 3°C/s max 6°C/s max. 200 150 Temperature pre-heating 100 150~200°C above 217°C 60~120s 60~150s 50 . 25℃ 0 50 100 150 200 250 300 (sec) Time

TAPE SPECIFICATIONS (units: mm)

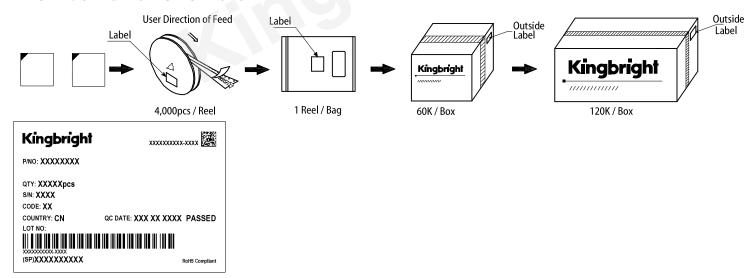


REEL DIMENSION (units: mm)



- 1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer
- to the latest datasheet for the updated specifications.

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